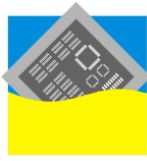


# ZESTRON® SD 301

## Cleaning medium for the removal of solder pastes, SMT adhesives and thick film pastes from stencils and screens



ZESTRON® SD 301 is an improved version of ZESTRON® SD 300 with reduced odor. The solvent-based cleaner removes solder pastes, SMT adhesives as well as thick film pastes from stencils and screens in spray-in-air systems. A faster drying time allows for shorter cleaning processes. Its high flash point permits both, manual usage and the application in printers and stencil cleaning equipment.

Areas of application: Stencil / Misprinted Board Cleaning		Additional product information:
SMT or conductive adhesives	++	<b>Application Recommendation:</b> Specific parameters for your cleaning process  <b>Technical Information Sheet 2:</b> Overview of pastes and fluxes tested  <b>Technical Information Sheet 3:</b> Material compatibility overview
Thick film pastes	++	
Low solid flux residues	o	
Solder paste (unsoldered)	++	
Rosin-based flux residues	+	
Water soluble flux residues	o	

++ highly recommended, best results      + recommended      0 possible

### Technical Centers - ① America ② Europe ③ Malaysia ④ East China ⑤ South China Cleaning Process Solutions under Production Floor Conditions



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:  
Phone: +1 (703) 393-9880; Email: [infoUSA@zestron.com](mailto:infoUSA@zestron.com)

### Advantages compared to other surfactant cleaners:

- Wide process window facilitates the removal of solder pastes, SMT adhesives and resistor pastes from stencils and screens as well as flux residues from misprinted assemblies.
- High loading capabilities, long bath life and therefore low cleaning costs.
- Due to a high flash point of 47°C / 117°F ZESTRON® SD 301 can be used in non-heated equipment without external explosion-protection systems.
- Non-halogenated, organic solvent-based cleaning agent.
- Used at ambient cleaning temperatures.
- Low odor, fast drying time.

Please refer to the material compatibility datasheet (Technical Information 3) prior to cleaning plastics.

Process	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air	ZESTRON® SD 301	ZESTRON® SD 301	Circulating or compressed air

Technical Data		
Density	g/ccm at 20°C / 68°F	0.88
Surface tension	mN/m at 25°C / 77°F	26.0
Boiling range	°C/°F	150 - 170 / 302 - 338
Flash point	°C/°F	47 / 117
pH-value	10g/l H <sub>2</sub> O	Neutral
Vapor pressure	(mbar) at 20°C/68°F	2
Cleaning temperature	°C/°F	Room temperature
Solubility in water		Soluble
Application concentration	Ready to use	Pure
HMIS rating	Health-Flammability-Reactivity	1 - 2 - 0

## PRODUCT FEATURES



Extensively tested and suitable for cleaning of lead-free solder pastes



100% compliance with EU guidelines (RoHS 1 & 2, WEEE)

### Environmental, health and safety regulations:

- ZESTRON® SD 301 does not contain halogenated compounds and is biodegradable.
- Water rinsing is not necessary. This results in the elimination of waste water.

### Availability:

- ZESTRON® SD 301 is available in 1L , 5L or 25L containers and 200L drums.

### Storage:

- Store ZESTRON® SD 301 in the original container at a temperature between 5-30°C / 41-86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

### Alternative product recommendation:

- For the water-based cleaning of stencils, we recommend the MPC® based product VIGON® SC 200.

# ZESTRON

**North Asia**  
Shanghai/Shenzhen-China  
infochina@zestron.com

**South Asia**  
Kulim-Malaysia  
infoasia@zestron.com

**America**  
Manassas, VA-USA  
infousa@zestron.com

**Europe**  
Ingolstadt-Germany  
info@zestron.com

